

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.04675	1.55	0.0558
	Doped silicon	Silicon (Si)	7440-21-3	2.96937	98.45	3.5442
			Subtotal	3.01612	100	3.6
Wire	Impurity	Non hazardous		0.00001	0.01	0.00001
	Pure metal	Copper (Cu)	7440-50-8	0.06597	99.99	0.07874
			Subtotal	0.06598	100	0.07875
Die Attach		Aromatic Polyester Resin	60088-52-0	0.00272	2.5	0.00325
		Paraffin wax	8002-74-2	0.00762	7.0	0.0091
		Epoxy resin system		0.02178	20.0	0.026
		Silver (Ag)	7440-22-4	0.07679	70.5	0.09165
			Subtotal	0.10891	100	0.13
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02557	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05115	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.17641	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	49.89519	97.55	59.55427
			Subtotal	51.14832	100	61.05
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.47755	100.0	0.57
			Subtotal	0.47755	100	0.57
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.67775	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.2924	9.5	5.12335
	Filler	Silica fused	60676-86-0	39.76114	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.45183	1.0	0.5393
			Subtotal	45.18312	100	53.93
			Total	100	100	119.35875

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